

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	491	UBM AND CHIP AND "257"/\$.CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/21 10:41
L2	9504	pad and wire adj bonding AND "257"/\$.CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/21 10:58
L3	294	pad and wire adj bonding adj machine AND "257"/\$.CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/21 12:14
L4	1	("6861763").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/21 12:14
S1	119	warp\$3 and 257/734	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/20 10:23
S2	1	("6825108").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/21 11:04
S3	1	("6242300").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/21 11:04
S4	1	("6168984").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/21 14:18
S5	1	"20030214011"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/21 14:18

S6	0	mold adj gate and lead adj package and 257/734	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/23 13:00
S7	0	mold adj gate and lead adj package and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/23 13:01
S8	0	molded adj gate and lead adj package and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/23 13:01
S9	2	molded adj gate and lead and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/03/23 13:01
S10	1	("5113581").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/20 13:10
S11	1	("6274978").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/20 15:56
S12	728	(257/782).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/20 17:20
S13	1425	(257/734).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/04/21 07:52